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**TMS 2018**  
147<sup>th</sup> Annual Meeting & Exhibition



**MARCH 11 – 15, 2018**  
**PHOENIX, ARIZONA**

**SUBMIT AN ABSTRACT TO:**

**ELECTRONIC MATERIALS**

**PHASE STABILITY, PHASE TRANSFORMATIONS, AND REACTIVE  
PHASE FORMATION IN ELECTRONIC MATERIALS XVII**

This is the 17th in a series of TMS symposia addressing the stability, transformation, and formation of phases during the fabrication, processing, and utilization of electronic materials and devices. Topics of interest range from microelectronic technologies to advanced energy technologies, including phase stability, transformation, formation, and morphological evolution of electronic packaging materials, interconnection materials, integrated circuit materials, and optoelectronic materials, as well as energy storage and generating materials.

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